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Part 16-4: Microwave integrated circuits – Switches**

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SEMICONDUCTOR DEVICES –

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International Standard IEC 60747-16-4 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

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SEMICONDUCTOR DEVICES –

Part 16-4: Microwave integrated circuits – Switches

1 Scope

This part of IEC 60747 provides new measuring methods, terminology and letter symbols, as well as essential ratings and characteristics for integrated circuit microwave switches.

There are many combinations for RF ports in switches, such as SPST (single pole single throw), SPDT (single pole double throw), SP3T (single pole triple throw), DPDT (double pole double throw), etc. Switches in this standard are based on SPDT. However, this standard is applicable to the other types of switches.

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The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

~~IEC 60617-12, Graphical symbols for diagrams – Part 12: Binary logic elements~~

~~IEC 60617-13, Graphical symbols for diagrams – Part 13: Analogue elements~~

~~IEC 60747-1(1983), Semiconductor devices – Discrete devices and integrated circuits – Part 1: General
Amendment 3 (1996)~~

IEC 60617, Graphical symbols for diagrams (available from <<http://std.iec.ch/iec60617>>)

IEC 60747-1:2006, Semiconductor devices – Part 1: General
IEC 60747-1:2006/AMD1:2010

IEC 60747-4, Semiconductor devices – Discrete devices – Part 4: Microwave devices

IEC 60747-16-1:2001, Semiconductor devices – Part 16-1: Microwave integrated circuits – Amplifiers

IEC 60747-16-1:2001/AMD1:2007

IEC 60747-16-1:2001/AMD2:2017

IEC 60748-2, Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits

IEC 60748-3, Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits

IEC 60748-4, Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits

IEC 61340-5-1:2007, Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements

IEC/TR 61340-5-2:2007, Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide

FINAL VERSION

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